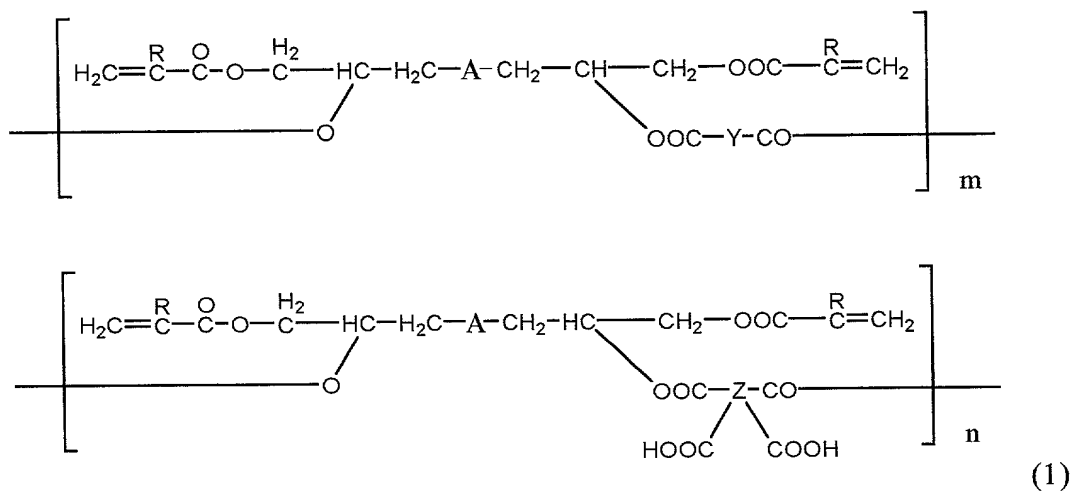


What is claimed is:

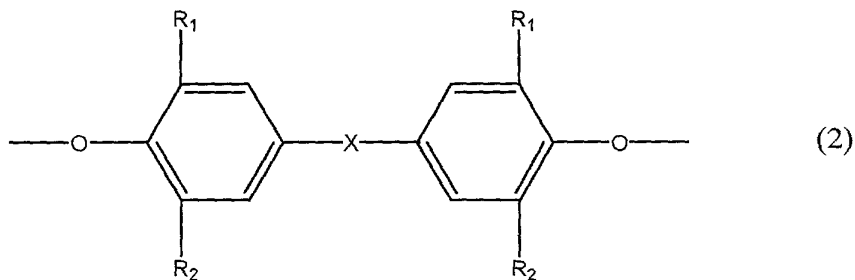
1. A photo- or heat-curable resin composition for forming a resin insulation layer in a printed wiring board comprising 0.01-5 parts by weight of an inorganic filler with its average particle diameter controlled in the range 5 nm-0.5 μ m per 100 parts by weight of the resin-forming component.

2. A photo- or heat-curable resin composition as described in claim 1 comprising

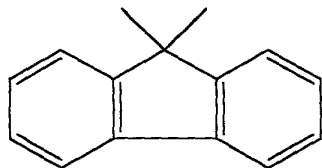
(A) 100 parts by weight of a photopolymerizable unsaturated compound represented by the following general formula (1)



wherein R is a hydrogen atom or a methyl group, A is a group represented by the formula (2)



(wherein R_1 and R_2 are independently hydrogen, an alkyl group with 1-5 carbon atoms, or a halogen), X is $-\text{CO}-$, $-\text{SO}_2-$, $-\text{C}(\text{CF}_3)_2-$, $-\text{Si}(\text{CH}_3)_2-$, $-\text{CH}_2-$, $-\text{O}-$, $-\text{S}-$,



or a direct bond, Y and Z are respectively the residue of a polycarboxylic acid or its acid anhydride, and m and n are the number of repeating units at a molar ratio m/n 0/100 - 100/0,

(B) 0-50 parts by weight of a compound containing an epoxy group, and

(C) 0-10 parts by weight of a photopolymerization initiator or sensitizer.

3. A photo- or heat-curable resin composition as described in claim 1 wherein the inorganic filler is silica sol.

4. A photo- or heat-curable resin composition as described in claim 1 wherein the resin-forming component comprises (A) 30-80% by weight of a photopolymerizable unsaturated compound, (B) 10-50% by weight of a compound containing an epoxy group, and 10-40% by weight of a polyfunctional acrylate, the inorganic filler is composed of silica sol with its average particle diameter controlled in the range 10-100 nm, and the

